ROHI	1
SEMICONDUCTO	R

## SMF7V5TF

Transient Voltage Suppressor

V <sub>RVM</sub>	7.5	V
PfP	200	W
lfP	15.5	А

Feature

High reliability Small mold type  Outline
Package Code SOD-123FL JEITA Code SC-109B ROHM Code PMDU
(1)
(2)
(2)
(1)
(1)Cathode (2)Anode

### Packaging Specification

ossed Tape
180
8
3000
TR
EW

Application
Surge Protection

Structure
Silicon Epitaxial Planar

• Absolute Maximum Rating  $(T_a = 25^{\circ}C)$ 

Parameter	Symbol	Conditions			Max.	Unit
Peak Pulse Power	P <sub>pp</sub>	tp=10/1000us			200	W
Peak Pulse Current	I <sub>pp</sub>	tp=10/1000us			15.5	А
Pow er dissipation	PD	on Glass-epoxy substrate		-	1	W
Junction temperature	Tj	-		-	150	°C
Storage temperature	T <sub>stg</sub>	-		-65	150	°C
ESD capability	Vron	IEC61000-4-2	Air	-	30	kV
	V <sub>ESD</sub>	IEC01000-4-2	Contact	-	30	kV

## (AEC-Q101 qualified) Data sheet

## SMFxxVTF Series

## ● Characteristic (Ta = 25°C)

	Symbol					Symbol					
P/N		rn voltage <sub>R</sub> (V)		e Current µA)	Clamping V <sub>CL</sub>	y voltage (V)	Reverse Stand-off voltage V <sub>RVM</sub> (V)				
	MN.	<del>ቨ</del> (mA)	MAX.	V <sub>R</sub> (V)	MAX.	Ipp(A)	MAX.				
SMF5V0TF	6.40	40	5.0	5.0	9.2	21.7	5.0				
SMF6V0TF	6.67	40	26	6.0	10.3	19.4	6.0				
SMF6V5TF	7.72	40	20	6.5	11.2	17.9	6.5				
SMF7V0TF	7.78	40	3.0	7.0	12.0	16.7	7.0				
SMF7V5TF	8.33	40	0.1	7.5	12.9	15.5	7.5				
SMF8V0TF	8.89	40	0.1	8.0	13.6	14.7	8.0				
SMF9V0TF	10.0	40	0.1	9.0	15.4	13.0	9.0				
SMF10VTF	11.1	20	0.1	10	17.0	11.8	10				
SMF11VTF	12.2	20	0.1	11	18.2	11.0	11				
SMF12VTF	13.3	20	0.1	12	19.9	10.1	12				
SMF13VTF	14.4	20	0.1	13	21.5	9.3	13				
SMF14VTF	15.6	20	0.1	14	23.2	8.6	14				
SMF15VTF	16.7	20	0.1	15	24.4	8.2	15				
SMF16VTF	17.2	20	0.1	16	26.0	7.7	16				
SMF18VTF	20.0	20	0.1	18	29.2	6.8	18				
SMF20VTF	22.2	10	0.1	20	32.4	6.2	20				
SMF22VTF	24.4	10	0.1	22	35.5	5.6	22				
SMF24VTF	26.7	10	0.1	24	38.9	5.1	24				
SMF26VTF	28.9	10	0.1	26	42.1	4.8	26				
SMF28VTF	31.1	10	0.1	28	45.4	4.4	28				
SMF30VTF	33.3	10	0.1	30	48.4	4.1	30				
SMF33VTF	36.7	10	0.1	33	53.3	3.8	33				

V<sub>BR</sub> test time is 40ms.

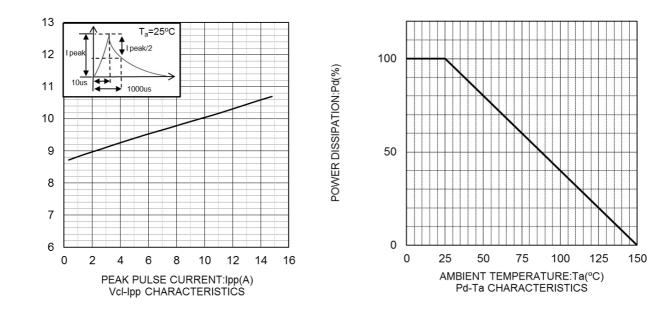
Marking

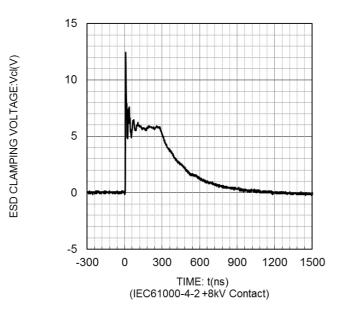
P/N	Marking	P/N	Marking
SMF5V0TF	AW	SMF14VTF	MW
SMF6V0TF	BW	SMF15VTF	NW
SMF6V5TF	CW	SMF16VTF	PW
SMF7V0TF	DW	SMF18VTF	QW
SMF7V5TF	EW	SMF20VTF	RW
SMF8V0TF	FW	SMF22VTF	SW
SMF9V0TF	GW	SMF24VTF	TW
SMF10VTF	HW	SMF26VTF	W
SMF11VTF	JW	SMF28VTF	VW
SMF12VTF	KW	SMF30VTF	WW
SMF13VTF	LW	SMF33VTF	XW



## Characteristic Curves

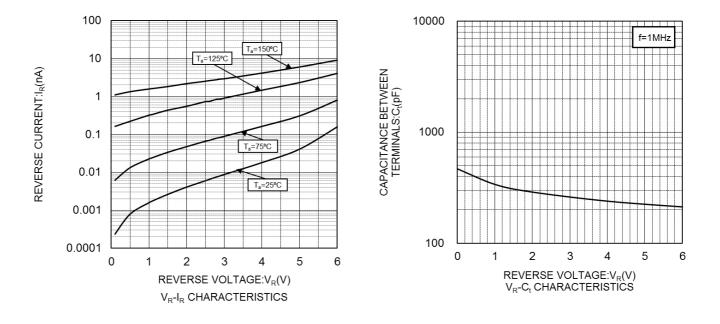
CLAMPING VOLTAGE:Vol(V)

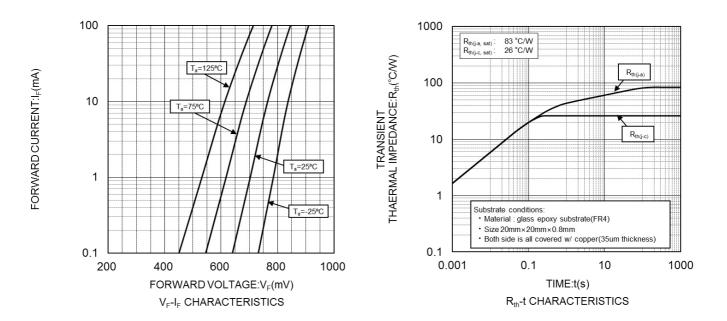






## Characteristic Curves



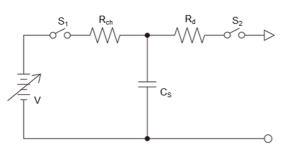




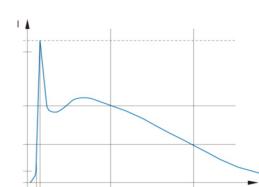
### Appended figure

Procedure to obtain ESD Clamping Voltage IEC61000-4-2 Spec

Level	Test Voltage (kV)	First Peak Current (A)	Current at 30ns (A)	Current at 60ns (A)
1	2	7.5	4	2
2	4	15	8	4
3	6	22.5	12	6
4	8	30	16	8

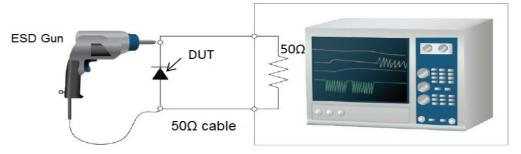


 $\begin{array}{ll} C_S:150 p F & R_d:330 \, \Omega \\ simplified \ diagram \ in \ ESD \ machine \end{array}$ 



IEC61000-4-2 Waveform

30n 60n tr=0.6 to 1ns

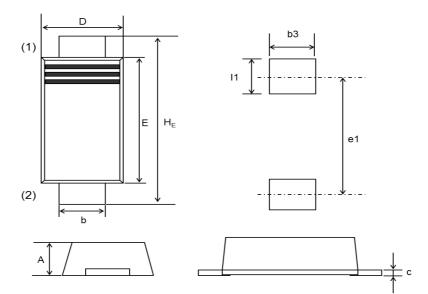


oscilloscope

- 1. Set up ESD Tester at IEC61000-4-2 condition. (IEC61000-4-2 : C=150pF, R=330 Ω)
- 2. Mount a sample on the high frequency test board with the SMA connector.
- Connect the SMA connector to the oscilloscope by 50Ωcable.
  Then, add the 10X-attenuator between test board and the cable to protect the oscilloscope.
- 4. Discharge ESD in contact discharge mode at any voltage. (normally 8kV Max.)



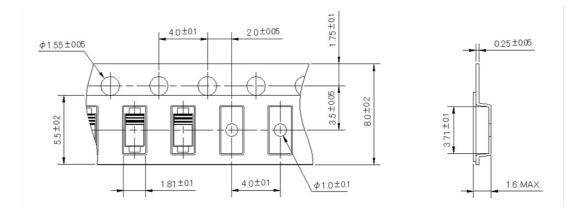
#### Dimensions (SOD-123FL SC-109B PMDU)



DIM		Milimeters		Inches		
DIVI	Min.	Average	Max.	Min.	Average	Max.
A	0.70	0.80	0.90	0.028	0.031	0.035
b	0.80	0.90	1.00	0.031	0.035	0.039
с	0.05	0.10	0.20	0.002	0.004	0.008
D	1.50	1.60	1.70	0.059	0.063	0.067
E	2.50	2.60	2.70	0.098	0.102	0.106
HE	3.38	3.50	3.62	0.133	0.138	0.143
l1	-	0.85	-	-	0.033	-
b3	-	1.20	-	-	0.047	-
e1	-	3.05	-	-	0.120	-

(1) The marking bar indicates the cathode.(2) The direction indicates the anode.

## Taping (Unit:mm)





# Notice

#### **Precaution on using ROHM Products**

1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment <sup>(Note 1)</sup>, aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

JAPAN	USA	EU	CHINA
CLASSI	CLASSⅢ	CLASS II b	CLASSII
CLASSⅣ	CLASSI	CLASSⅢ	CLASSII

2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:

[a] Installation of protection circuits or other protective devices to improve system safety

[b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure

- 3. Our Products are not designed under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

#### Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- 2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

#### **Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

#### **Precaution for Product Label**

A two-dimensional barcode printed on ROHM Products label is for ROHM's internal use only.

#### **Precaution for Disposition**

When disposing Products please dispose them properly using an authorized industry waste company.

#### Precaution for Foreign Exchange and Foreign Trade act

Since concerned goods might be fallen under listed items of export control prescribed by Foreign exchange and Foreign trade act, please consult with ROHM in case of export.

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